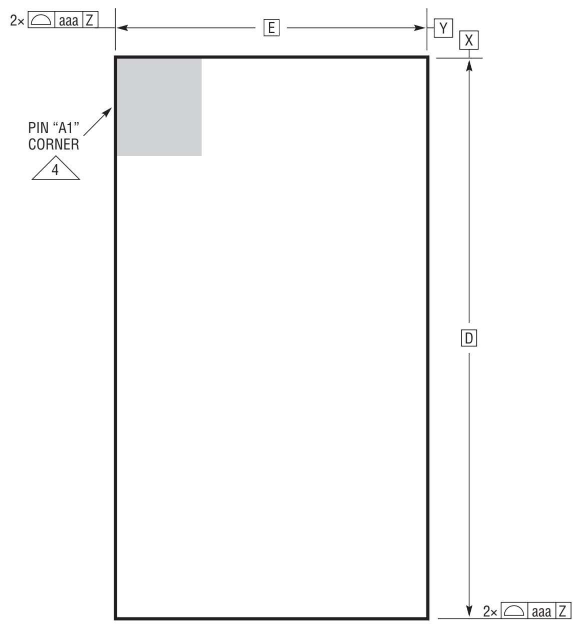
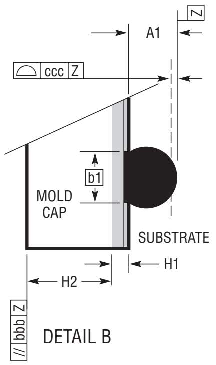
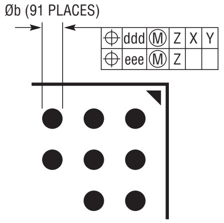
BGA Package
91-Lead (11.25mm × 6.25mm × 2.22mm)
(Reference LTC DWG# 05-08-1608 Rev 0)



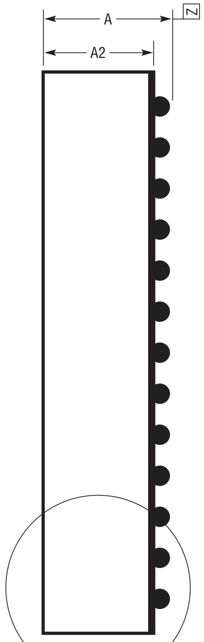
PACKAGE TOP VIEW



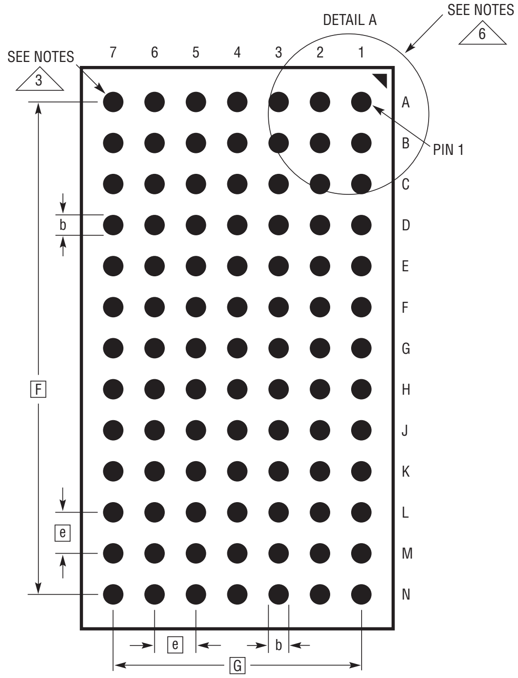
DETAIL B



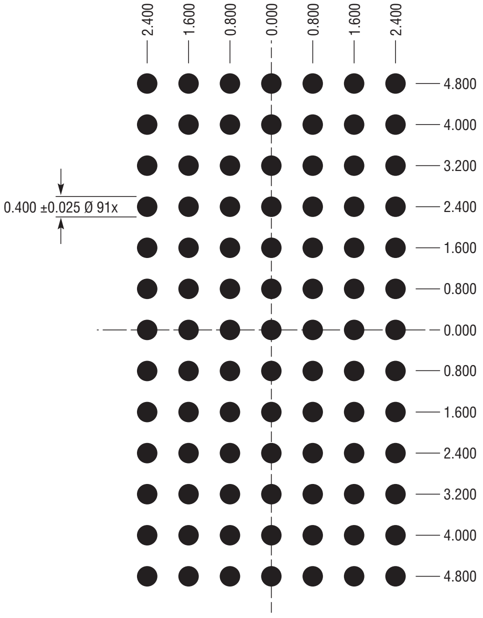
DETAIL A



DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	2.03	2.22	2.41	
A1	0.30	0.40	0.50	BALL HT
A2	1.73	1.82	1.91	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		11.25		
E		6.25		
e		0.80		
F		9.60		
G		4.80		
H1		0.32		SUBSTRATE THK
H2		1.50		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 91

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

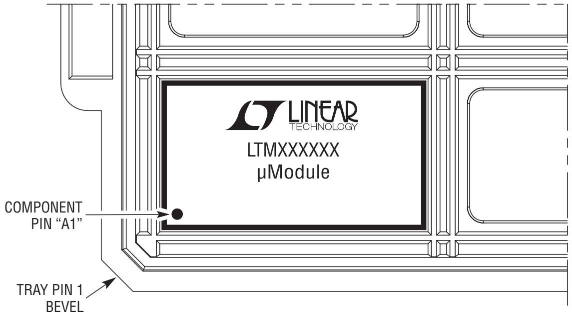
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION